

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPG20N04S4-18A	**Issued**	24. February 2022
MA#	MA005700090		
Package	PG-TDSON-8-10	**Weight***	98.58 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.562	0.57	0.57	5698	5698
chip_2	inorganic material	silicon	7440-21-3	0.562	0.57	0.57	5698	5698
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		133	
	non noble metal	iron	7439-89-6	0.044	0.04		444	
	non noble metal	copper	7440-50-8	43.681	44.32	44.37	443105	443682
wire	non noble metal	aluminium	7429-90-5	0.803	0.82	0.82	8150	8150
encapsulation	organic material	carbon black	1333-86-4	0.093	0.09		943	
	plastics	epoxy resin	-	6.598	6.69		66929	
	inorganic material	silicondioxide	60676-86-0	39.773	40.35	47.13	403458	471330
leadfinish	non noble metal	tin	7440-31-5	1.396	1.42	1.42	14165	14165
plating	inorganic material	phosphorus	7723-14-0	0.001			15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6118	6133
solder	non noble metal	tin	7440-31-5	0.035	0.04		355	
	noble metal	silver	7440-22-4	0.044	0.04		443	
	non noble metal	lead	7439-92-1	1.669	1.69	1.77	16934	17732
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			27	
	non noble metal	copper	7440-50-8	2.699	2.74	2.74	27377	27412
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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